



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



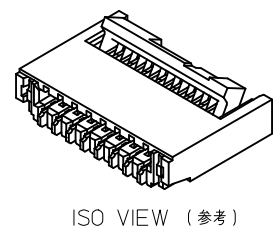
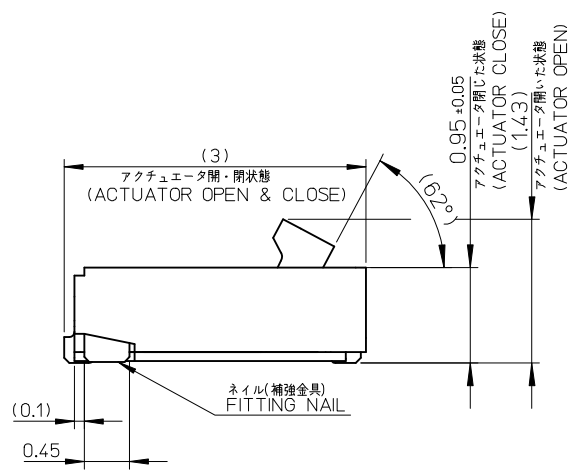
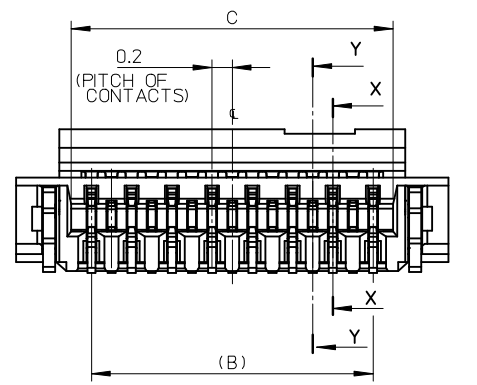
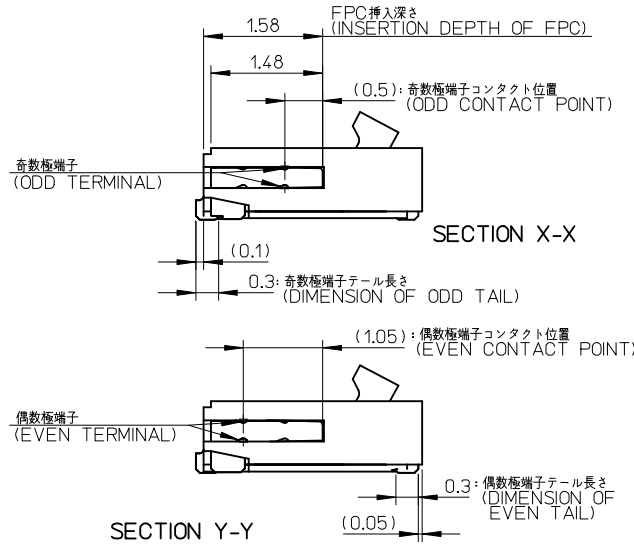
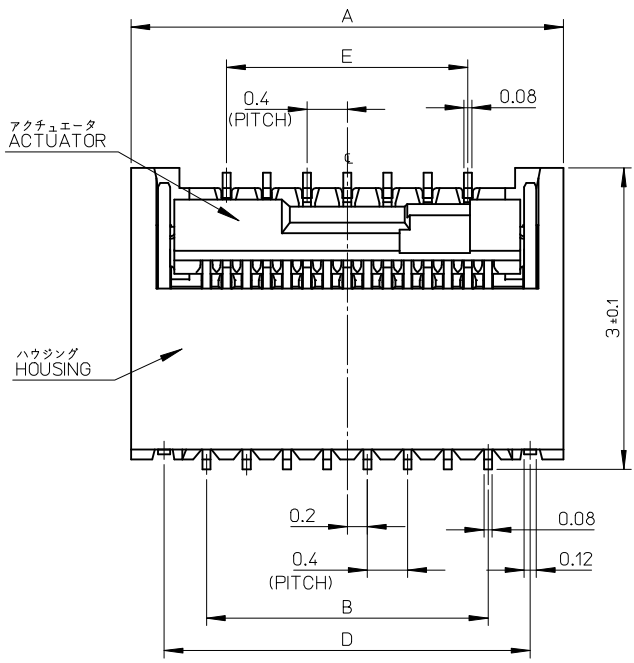
## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ISO VIEW (参考)

注記 NOTES:

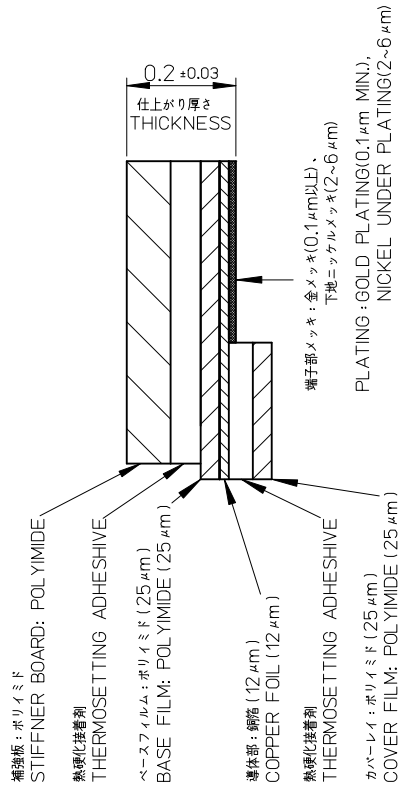
- 材質 MATERIAL  
ハウジング: 液晶ポリマー(LCP)、黒色、ガラス充填、UL94 V-0  
アクチュエータ: ホリアミド樹脂(PA)、灰色、ガラス充填、UL94 HB  
奇数端子・偶数端子: 焼青銅(t=0.08)、ニッケル下地・金メッキ  
ネイル(補強金具): 焼青銅(t=0.12)、ニッケル下地・錫メッキ  
HOUSING: LIQUID CRYSTAL POLYMER, BLACK, GLASS FILLED, UL94 V-0  
ACTUATOR: POLYAMIDE, GRAY GLASS FILLED, UL94 HB  
TERMINAL: PHOSPHOR BRONZE (t=0.08), GOLD OVER NICKEL PLATING  
FITTING NAIL: PHOSPHOR BRONZE (t=0.12), TIN OVER NICKEL PLATING
- めっき仕様 PLATING  
ターミナル TERMINAL  
接点部: 金メッキ 0.1μm以上  
テール部: 金メッキ  
下地: ニッケルメッキ 1.0μm以上  
CONTACT AREA: GOLD PLATING 0.1μm MINIMUM  
TAIL AREA: GOLD PLATING  
UNDER PLATING: NICKEL PLATING 1.0μm MINIMUM  
ネイル(補強金具) FITTING NAIL  
錫めっき 1.0μm以上  
下地: ニッケルめっき: 1.0μm以上  
TIN PLATING 1.0μm MINIMUM  
UNDER PLATING: NICKEL PLATING 1.0μm MINIMUM
- 端子・ネイルの平坦度は、0.1mm以下とする。  
COPLANARITY OF TAILS AND FITTING NAILS: 0.1 MAXIMUM.
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

0.064	11.6	12.84	12.4	12	13.5	504070-6191	61
0.054	9.6	10.84	10.4	10	11.5	504070-5191	51
0.043	7.2	8.44	8	7.6	9.1	504070-3991	39
重さ (g) WEIGHT (g)	E	D	C	B	A	EMBOSSED PACKAGE オーダー番号: ORDER NO.	極数 CIRCUITS

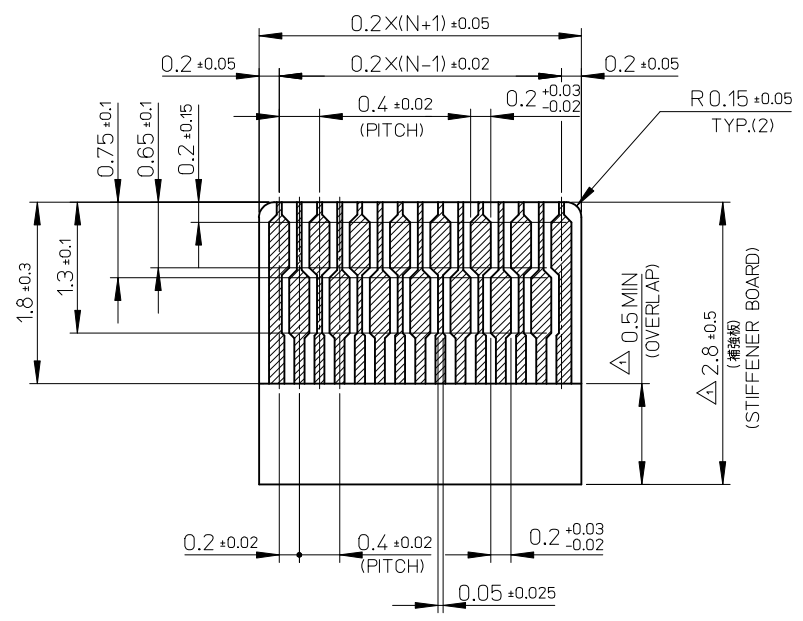
CONNECTOR SERIES NO. : 504070-\*\*\*11

PROPOSED EC NO: J2013-0279 DRWN: JEBISAWA 2012/04/26 CHKD: HIJIMA 2012/06/28 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY JEBISAWA	DATE 2012/04/26	TITLE 0.2 FPC CONN. BACK FLIP HOUSING ASSY LOW-HALOGEN		
	10 OVER 30 UNDER	±0.25	CHECKED BY HIJIMA	DATE 2012/04/26			
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/02/19			
	ANGULAR ±1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-504070-001	SHEET NO. 1 OF 2	
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

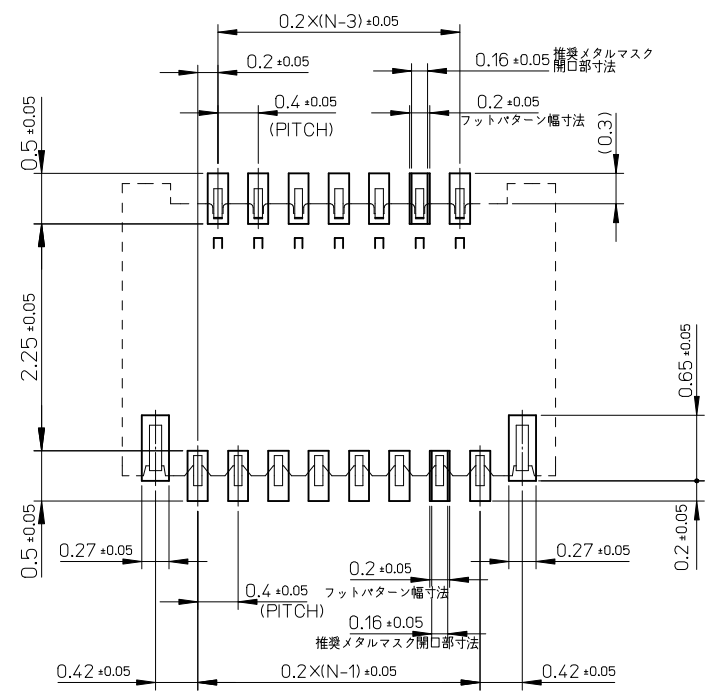
10 9 8 7 6 5 4 3 2 1



FPC構成推奨仕様  
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法  
APPLICABLE FPC OF GOLD PLATING  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.2 ± 0.03)  
(THICKNESS: 0.2 ± 0.03)



推奨基板寸法  
RECOMMENDED  
P.C.B. PATTERN LAYOUT

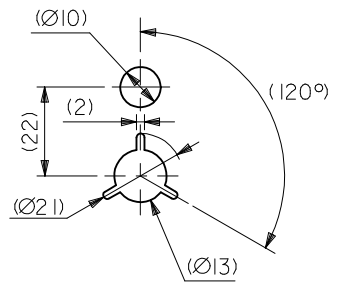
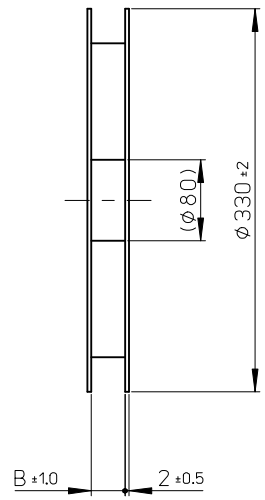
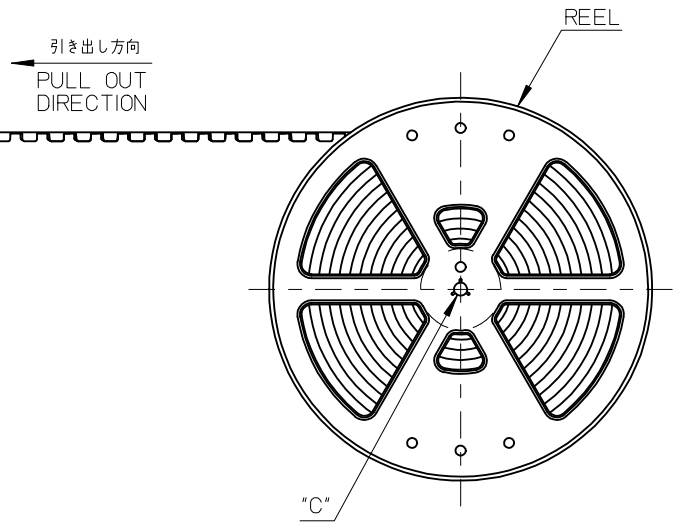
推奨ベース厚 : 100µm  
推奨マスク開口率 : 80%  
RECOMMEND SCREEN THICKNESS : 100µm  
RECOMMEND SCREEN OPEN RATIO : 80%

・FPCについて(ABOUT FPC):  
抜き方向は、導体側から補強板側を推奨致します。  
補強フィルム材質は、ポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED MATERIAL: STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE  
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください  
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2013-0279 DRWN: JEBISAWA 2012/04/26 CHKD: H I J I M A 2012/06/28 APPR: YNOGAWA 2014/02/19	DESCRIPTION REV 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY JEBISAWA	DATE 2012/04/26	TITLE 0.2 FPC CONN. BACK FLIP HOUSING ASSY LOW-HALOGEN			
		10 OVER 30 UNDER	± 0.25	CHECKED BY H I J I M A	DATE 2012/04/26	molex			
		30 OVER	± 0.3	APPROVED BY YNOGAWA	DATE 2014/02/19				
ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-504070-001		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

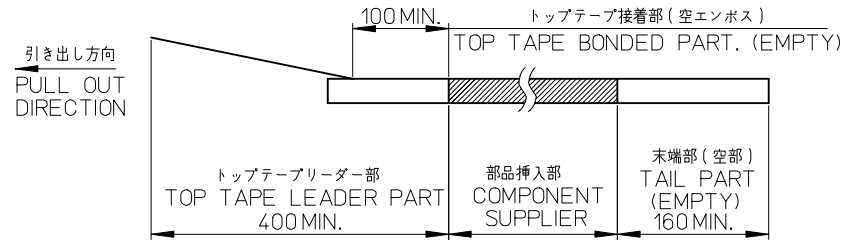
9 8 7 6 5 4 3 2



DETAIL "C"

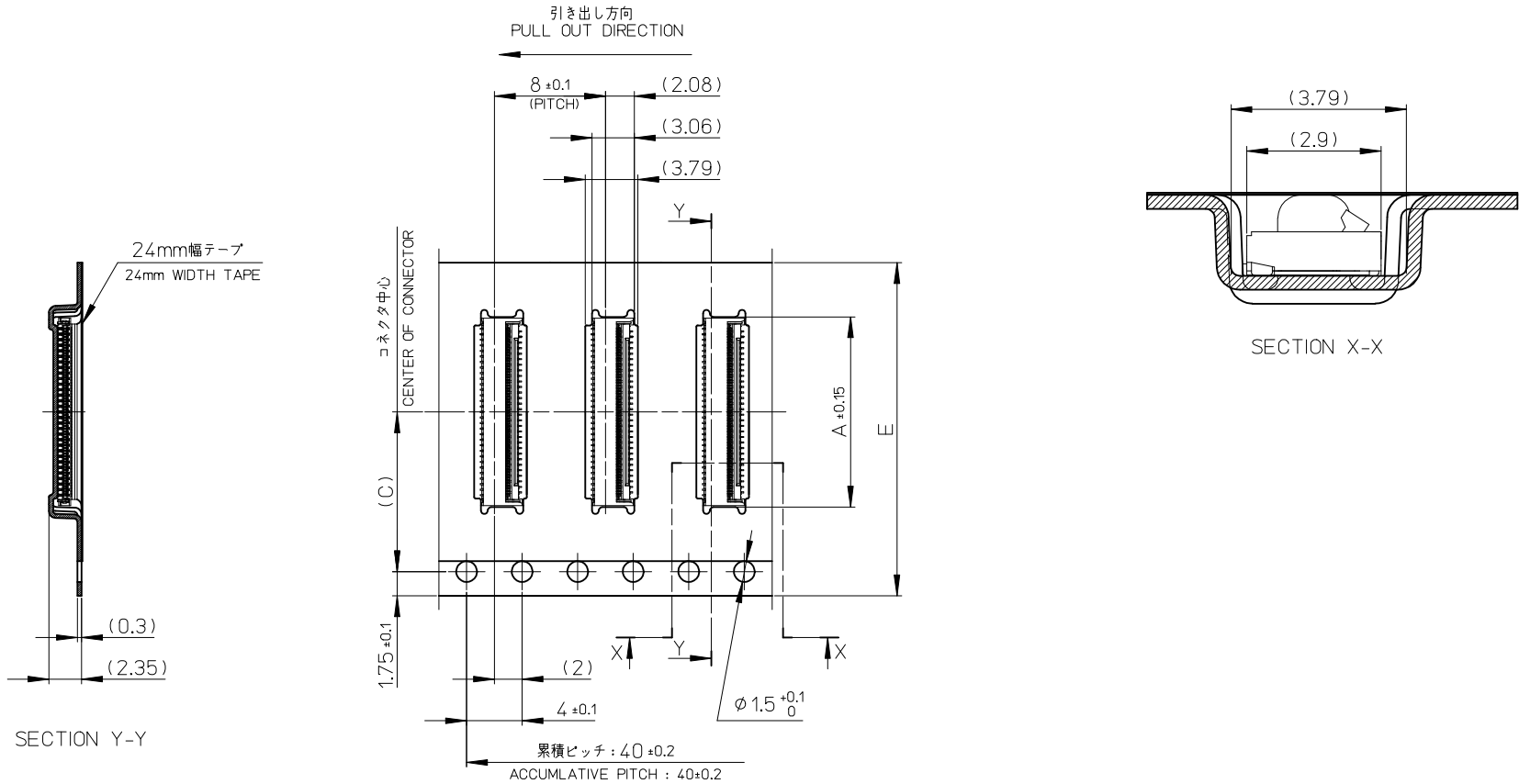
注記 NOTES

- 製品詳細寸法については図面 RSD-504070-001 を参照下さい。  
REFER TO THE RSD-504070-001 ABOUT DIMENSIONS IN DETAIL.
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS：3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- 材料 MATERIAL  
 キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYRENE)  
 トップテープ (TOP TAPE)：PET, PE, PEF  
 リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS 適合品  
 ELV AND ROHS COMPLIANT

PROPOSED EC NO.: J2013-0279 DRWN: TUEDA 2014/02/03 CHKD: HIJIMA 2014/02/04 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY TUEDA	DATE 2014/02/03	TITLE 0.2 FPC CONN. BACK FLIP TAPING PACKAGE (504070-**11 SERIES)	
	10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA	DATE 2014/02/04		
	30 OVER	± ---	APPROVED BY YNOGAWA	DATE 2014/02/19		
ANGULAR ±1 °		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-504070-002	SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



24±0.3	11.5	25.4	13.7	504070-6191	61
			11.7	504070-5191	51
			9.3	504070-3991	39
E キャリアテープ幅 EMBOSSED TAPE WIDTH	C	B	A	オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO.: J2013-0279 DRWN: TUEDA 2014/02/03 CHKD: HIJIMA 2014/02/04 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	± ---	TUEDA	2014/02/03	0.2 FPC CONN. BACK FLIP TAPING PACKAGE (504070-**11 SERIES)					
	30 OVER	± ---	CHECKED BY	DATE						
	ANGULAR	±1 °	HIJIMA	2014/02/03						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		YNOGAWA	2014/02/19	SEE CHART		SD-504070-002		2 OF 2		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								